Oxidative Addition

An **oxidative addition** reaction is one in which (usually) a neutral ligand adds to a metal center. In doing so it oxidizes the metal, typically by 2e-.

After oxidative addition, the co-ordination number of the metal typically increases by 2.

Generally, transferring of the two electrons from the metal to the incoming ligand breaks a bond in that ligand forming two new anionic ligands.

two new anionic

hydride ligands

Oxidative Addition

Three main types of molecules (substrates) can perform oxidative additions to metal centers:

Non-electrophillic,

Non-electrophillic "intact",

Electrophillic.

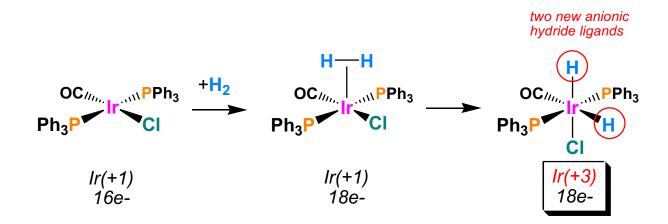
Oxidative Addition - Non-electrophillic:

These molecules do NOT contain electronegative atoms and/or are not good oxidizing agents.

H₂, C-H bonds, Si-H bonds, S-H bonds, B-H bonds, N-H bonds, S-S bonds and C-C bonds.

Often considered to be "non-reactive" substrates (except H₂).

Generally require the presence of an **empty orbital** on the metal center in order for them to pre-coordinate prior to being activated for the oxidative addition reaction



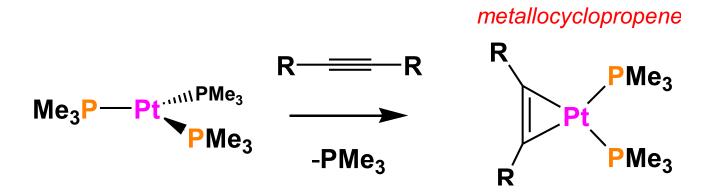
Oxidative Addition –

Non-electrophillic "Intact":

The neutral molecules may or may not contain electronegative atoms, but do need to have a **double** or **triple bond**.

One needs a metal center with an **empty orbital** (16e- or lower count) in order to pre-coordinate the ligand before the oxidative addition occurs.

alkenes, alkynes, and O₂



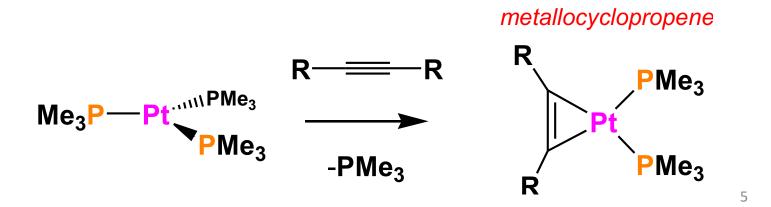
Oxidative Addition -

Non-electrophillic "Intact":

Unlike most of the other substrate molecules that break a single bond and form two separate anionic ligands upon the oxidative addition, these ligands have double or triple bonds and only **one** of the π -bonds is broken leaving the σ -bond intact.

Notably, the ligand does pick up two electrons from the metal and becomes a dianionic ligand.

alkenes, alkynes, and O₂

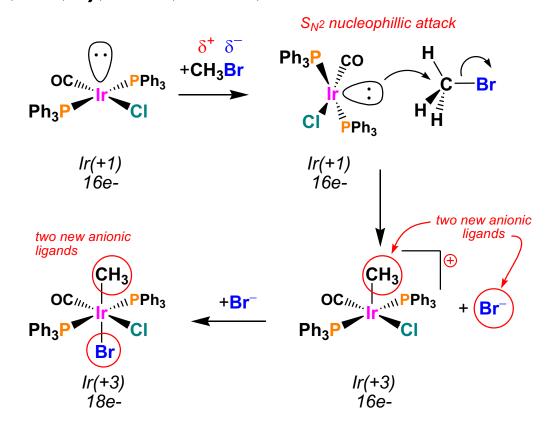


Oxidative Addition – *Electrophillic:*

These molecules **do** contain electronegative atoms and are good oxidizing agents.

They are often considered to be "reactive" substrates.

$$X2 (X = CI, Br, I), R-X, Ar-X, H-X$$



Oxidative Addition - General Features:

Oxidative addition involves oxidation (removal of electrons) of the metal center. Hence, the more **electron-rich** the metal, the more easier is the oxidative addition to the metal center.

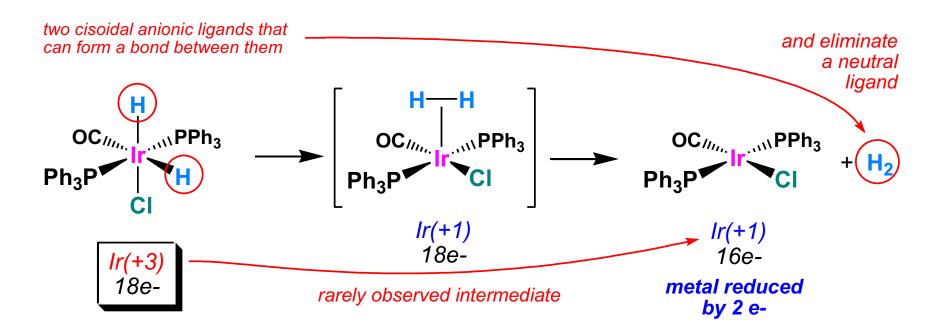
In comparing two or more metal complexes to see which will be the most reactive towards a particular substrate for oxidative addition, one would pick the metal center with the *strongest donor* ligands, fewest π -acceptor ligands, or most negative charge.

Note that the non-electrophillic ligands and "intact" ligands usually require that there is an *empty orbital* (16e- or lower) on the metal center in order to react.

Reductive Elimination

A *reductive elimination* reaction is the reverse of an oxidative addition.

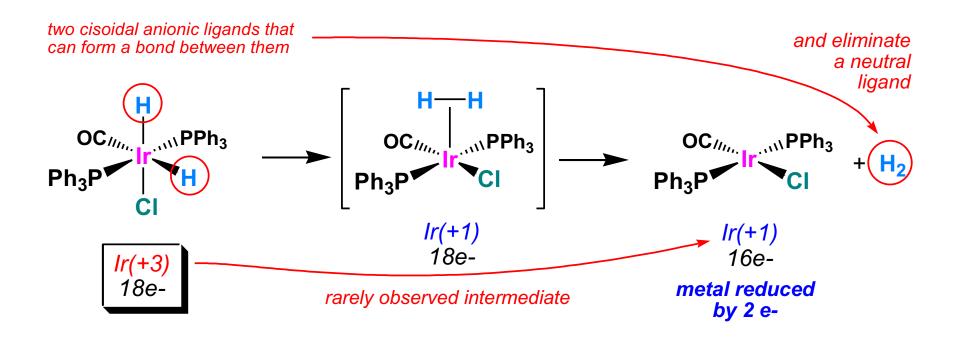
It is a reaction in which **two cisoidal anionic ligands** on a metal center couple together.



Reductive Elimination

Each anionic ligand pushes one electron back onto the metal center to reduce it by 2e-.

The coupled anionic ligands then usually fall off the metal center as a **neutral** molecule.



Reductive Elimination - General Features:

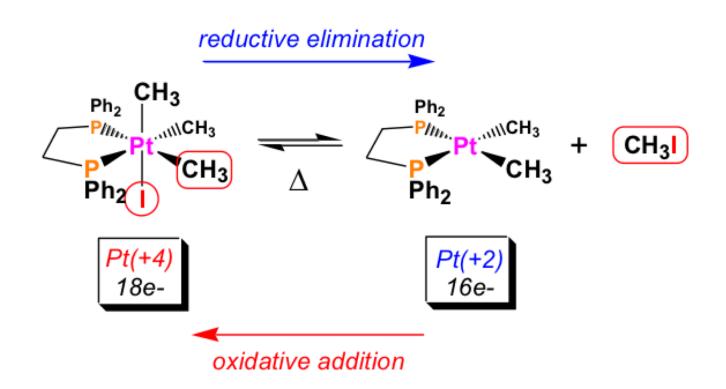
Since *electron-rich* metal complexes favor **oxidative addition**, the reverse is true for reductive elimination.

Electron deficient metal centres favor reductive elimination.

This can be accomplished by having more π -acceptor ligands, cationic charge(s), and/or coordinative unsaturation (lower than 18e-count).

While *reductive elimination* can occur from saturated 18e-complexes (as long as the two ligands that you want to reductively eliminate are *cisoidal* to one another), it has been shown that reductive elimination can be promoted by a ligand dissociation generating an unsaturated and more electron-deficient metal center.

Reductive Elimination – Kinetic Preference:



Reductive Elimination – *Thermodynamic Preference:*

